

ON Semiconductor®

#### FDB8442-F085

# N-Channel PowerTrench® MOSFET 40V, 80A, 2.9m $\Omega$

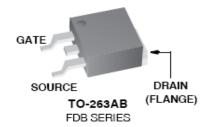
#### **Features**

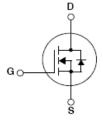
- Typ  $r_{DS(on)} = 2.1 \text{m}\Omega$  at  $V_{GS} = 10 \text{V}$ ,  $I_D = 80 \text{A}$
- Typ  $Q_{g(10)} = 181$ nC at  $V_{GS} = 10$ V
- Low Miller Charge
- Low Q<sub>rr</sub> Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant



#### **Applications**

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter / Alternator
- Distributed Power Architectures and VRMs
- Primary Switch for 12V Systems





Тур

Max

Units

Min

### $\textbf{MOSFET Maximum Ratings} \ \, \textbf{T}_{C} = 25^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	40	V
$V_{GS}$	Gate to Source Voltage	±20	V
	Drain Current Continuous (T <sub>C</sub> <158 °C, V <sub>GS</sub> = 10V)	80	
ID	Drain Current Continuous ( $T_{amb} = 25^{\circ}C$ , $V_{GS} = 10V$ , with $R_{\theta,JA} = 43^{\circ}C/W$ )	28	Α
	Pulsed	See Figure 4	
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	720	mJ
	Power Dissipation	254	W
P <sub>D</sub>	Derate above 25°C	1.7	W/°C
T <sub>.I</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to +175	οС

#### **Thermal Characteristics**

$R_{\theta,JC}$	Thermal Resistance Junction to Case	0.59	°C/W
R <sub>a.IA</sub>	Thermal Resistance Junction to Ambient TO-263, lin <sup>2</sup> copper pad area	43	°C/W

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8442	FDB8442-F085	TO-263AB	330mm	24mm	800 units

#### **Electrical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

Parameter

Off Characteristics							
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V	
	Zana Oata Vallana Busia Oanad	V <sub>DS</sub> = 32V	-	-	1		
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{GS} = 0V$ $T_{J} = 150$	o°C -	-	250	μΑ	
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±20V	-	-	±100	nA	

#### **On Characteristics**

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	2.9	4	V
,		$I_D = 80A, V_{GS} = 10V$	-	2.1	2.9	
r <sub>DS(on)</sub>	Drain to Source On Resistance	I <sub>D</sub> = 80A, V <sub>GS</sub> = 10V, T <sub>.I</sub> = 175°C	-	3.6	5.0	mΩ

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance		-	12200	-	pF
Coss	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1MHz	-	1040	i	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	I = IMHZ	-	640	i	pF
$R_{G}$	Gate Resistance	$V_{GS} = 0.5V, f = 1MHz$	-	1.0	i	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	-	181	235	nC
Q <sub>g(TH)</sub>	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $V_{DD} = 20V$	-	23	30	nC
Qgs	Gate to Source Gate Charge	I <sub>D</sub> = 80A	-	49	i	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau	$I_g = 1mA$	-	26	i	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	41	i	nC

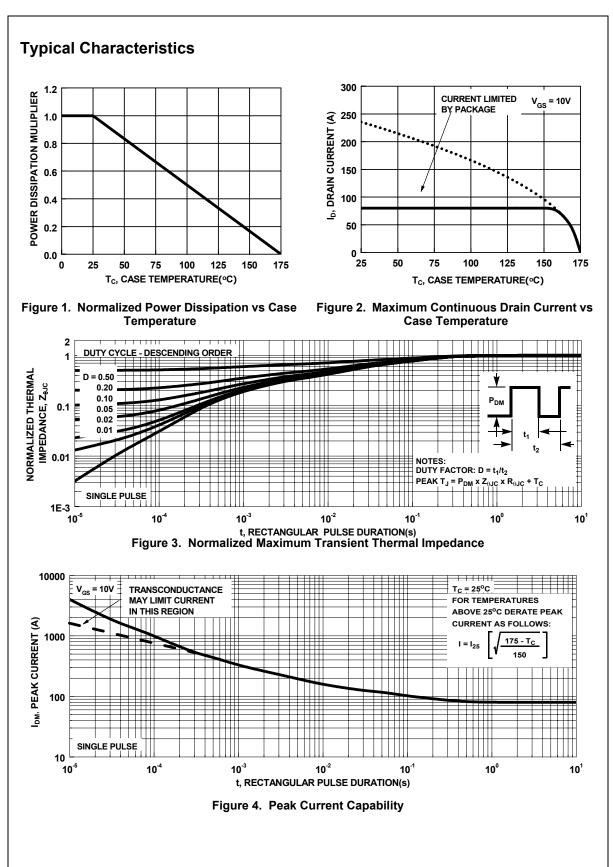
## Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise noted Symbol Parameter Test Condition

Symbo	DI Parameter	lest Conditions	IVIII	тур	IVIAX	Units
Switch	ning Characteristics					
t <sub>(on)</sub>	Turn-On Time		-	-	62	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	19.5	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 20V, I_D = 80A$	-	19.3	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 2\Omega$	-	57	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	17.2	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	118	ns

#### **Drain-Source Diode Characteristics**

V <sub>SD</sub>	On the Burk Birds William	I <sub>SD</sub> = 80A	-	0.9	1.25	V
	Source to Drain Diode Voltage	I <sub>SD</sub> = 40A	-	0.8	1.0	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 75A, di/dt = 100A/μs	-	49	64	ns
$Q_{rr}$	Reverse Recovery Charge	I <sub>F</sub> = 75A, di/dt = 100A/μs	-	70	91	nC

**Notes:** 1: Starting  $T_J = 25^{\circ}C$ , L = 0.35 mH,  $I_{AS} = 64 \text{A}$  2: Pulse width = 100s.



#### **Typical Characteristics**

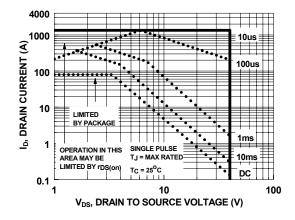


Figure 5. Forward Bias Safe Operating Area

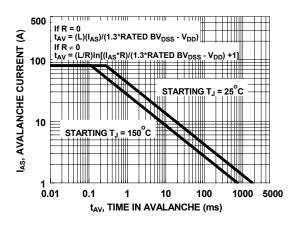


Figure 6. Unclamped Inductive Switching Capability

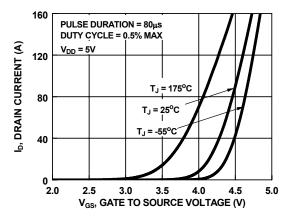


Figure 7. Transfer Characteristics

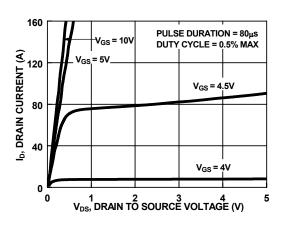


Figure 8. Saturation Characteristics

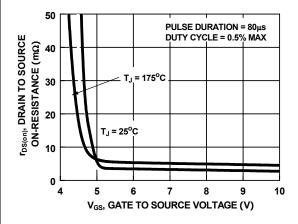


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

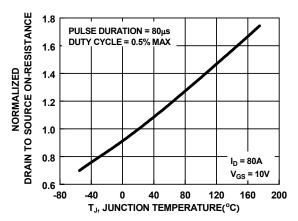


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

#### **Typical Characteristics**

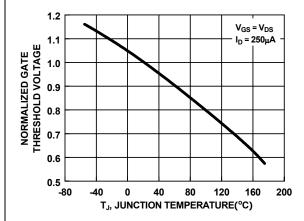


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

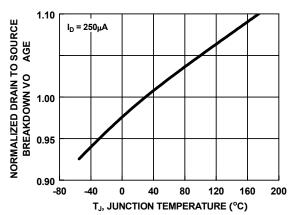


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

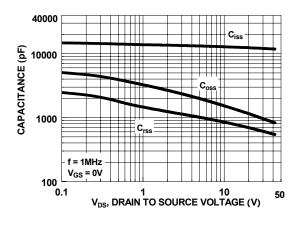


Figure 13. Capacitance vs Drain to Source Voltage

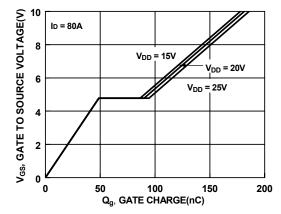


Figure 14. Gate Charge vs Gate to Source Voltage

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